



Material Content Data Sheet



Sales Product Name		IFX25401TEV		Issued		29. August 2013			
MA#		MA000723206							
Package		PG-TO252-5-11		Weight*		365.94 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.179	0.87	0.87	8687	8687	
leadframe	non noble metal	iron	7439-89-6	0.205	0.06		559		
	inorganic material	phosphorus	7723-14-0	0.061	0.02		168		
	non noble metal	copper	7440-50-8	204.243	55.81	55.89	558128	558855	
wire	non noble metal	aluminium	7429-90-5	0.179	0.05	0.05	488	488	
encapsulation	organic material	carbon black	1333-86-4	0.296	0.08		810		
	plastics	epoxy resin	-	13.631	3.72		37248		
	inorganic material	silicondioxide	60676-86-0	134.233	36.68	40.48	366816	404874	
leadfinish	non noble metal	tin	7440-31-5	5.072	1.39	1.39	13861	13861	
plating	non noble metal	nickel	7440-02-0	0.076	0.02		208		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	209	
solder	noble metal	silver	7440-22-4	0.119	0.03		326		
	non noble metal	tin	7440-31-5	0.095	0.03		261		
	non noble metal	lead	7439-92-1	4.552	1.24	1.30	12439	13026	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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